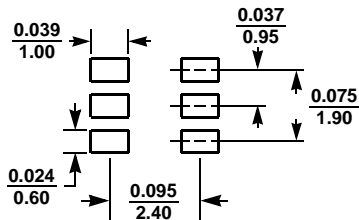
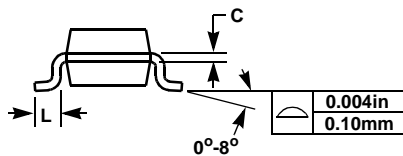
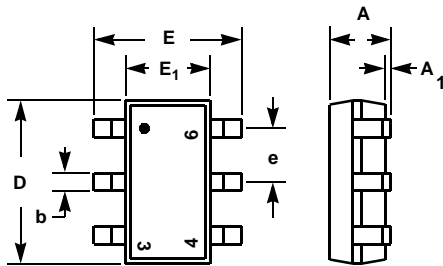


## MO-193AA (TSOP-6)

6 LEAD JEDEC MO-193AA TSOP PLASTIC PACKAGE  
(SIMILAR TO SSOT™-6)

**FAIRCHILD**  
SEMICONDUCTOR®



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.035	0.043	0.90	1.10	
A <sub>1</sub>	0.004		0.10		
b	0.012	0.020	0.30	0.50	
c	0.003	0.008	0.08	0.20	
D	0.107	0.122	2.70	3.10	2
E	0.103	0.118	2.60	3.00	
E <sub>1</sub>	0.056	0.070	1.40	1.80	3
e	0.037 BS		0.95 BSC		
L	0.014	0.021	0.35	0.55	4

### NOTES:

1. All dimensions are within the allowable dimensions of Rev. B of JEDEC MO-193AA outline dated 10-99.
2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.006 inches (0.15mm) per side.
3. Dimension "E" does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 0.006 inches (0.15mm) per side.
4. "L" is the length of terminal for soldering.
5. Controlling dimension: Millimeter.
6. Revision 2 dated 5-00.

SSOT™-6 is a trademark of Fairchild Semiconductor.